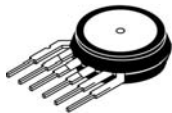
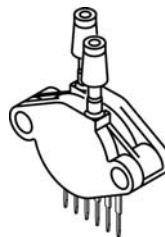


**UNIBODY PACKAGES**

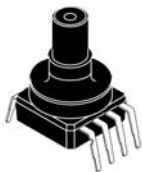
**MPX5050D**  
**CASE 867-08**



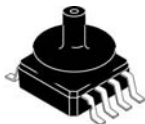
**MPX5050GP**  
**CASE 867B-04**



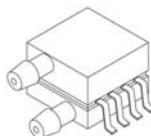
**MPX5050DP**  
**CASE 857C-05**

**SMALL OUTLINE PACKAGES**

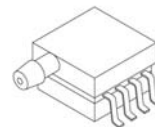
**MPVZ5050GW7U**  
**CASE 1560-03**



**MPXV5100GC6U**  
**CASE 482A-01**



**MPXV5050DP**  
**CASE 1351-01**



**MPXV5050GP**  
**CASE 1369-01**

## Operating Characteristics

**Table 1. Operating Characteristics** ( $V_S = 5.0$  Vdc,  $T_A = 25^\circ\text{C}$  unless otherwise noted,  $P_1 > P_2$ . Decoupling circuit shown in Figure 4 required to meet electrical specifications.)

Characteristic	Symbol	Min	Typ	Max	Unit
Pressure Range <sup>(1)</sup>	$P_{OP}$	0	—	50	kPa
Supply Voltage <sup>(2)</sup>	$V_S$	4.75	5.0	5.25	Vdc
Supply Current	$I_o$	—	7.0	10	mAdc
Minimum Pressure Offset <sup>(3)</sup> @ $V_S = 5.0$ Volts	$V_{off}$	0.088	0.2	0.313	Vdc
Full Scale Output <sup>(4)</sup> @ $V_S = 5.0$ Volts	$V_{FSO}$	4.587	4.7	4.813	Vdc
Full Scale Span <sup>(5)</sup> @ $V_S = 5.0$ Volts	$V_{FSS}$	—	4.5	—	Vdc
Accuracy <sup>(6)</sup>	—	—	—	$\pm 2.5$	% $V_{FSS}$
Sensitivity	V/P	—	90	—	mV/kPa
Response Time <sup>(7)</sup>	$t_R$	—	1.0	—	ms
Output Source Current at Full Scale Output	$I_{o+}$	—	0.1	—	mAdc
Warm-Up Time <sup>(8)</sup>	—	—	20	—	ms
Offset Stability <sup>(9)</sup>	—	—	$\pm 0.5$	—	% $V_{FSS}$

1. 1.0 kPa (kiloPascal) equals 0.145 psi.

2. Device is ratiometric within this specified excitation range.

3. Offset ( $V_{off}$ ) is defined as the output voltage at the minimum rated pressure.

4. Full Scale Output ( $V_{FSO}$ ) is defined as the output voltage at the maximum or full rated pressure.

5. Full Scale Span ( $V_{FSS}$ ) is defined as the algebraic difference between the output voltage at full rated pressure and the output voltage at the minimum rated pressure.

6. Accuracy (error budget) consists of the following:

Linearity: Output deviation from a straight line relationship with pressure over the specified pressure range.

Temperature Hysteresis: Output deviation at any temperature within the operating temperature range, after the temperature is cycled to and from the minimum or maximum operating temperature points, with zero differential pressure applied.

Pressure Hysteresis: Output deviation at any pressure within the specified range, when this pressure is cycled to and from the minimum or maximum rated pressure at  $25^\circ\text{C}$ .

TcSpan: Output deviation over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .

TcOffset: Output deviation with minimum pressure applied, over the temperature range of  $0^\circ$  to  $85^\circ\text{C}$ , relative to  $25^\circ\text{C}$ .

Variation from Nominal: The variation from nominal values, for Offset or Full Scale Span, as a percent of  $V_{FSS}$  at  $25^\circ\text{C}$ .

7. Response Time is defined as the time for the incremental change in the output to go from 10% to 90% of its final value when subjected to a specified step change in pressure.

8. Warm-up Time is defined as the time required for the product to meet the specified output voltage after the Pressure has been stabilized.

9. Offset Stability is the product's output deviation when subjected to 1000 hours of Pulsed Pressure, Temperature Cycling with Bias Test.

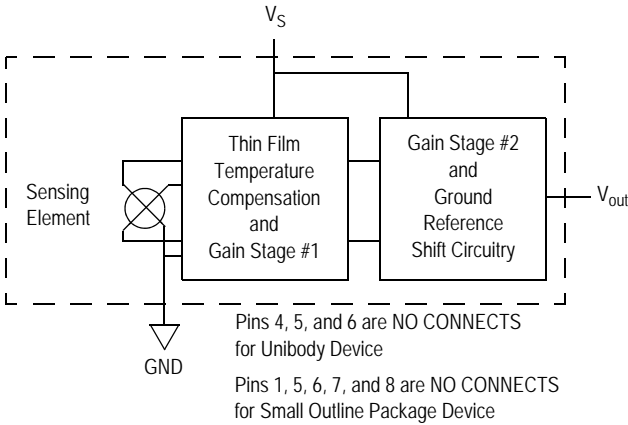
## Maximum Ratings

**Table 2. Maximum Ratings<sup>(1)</sup>**

Rating	Symbol	Value	Unit
Maximum Pressure (P1 > P2)	P <sub>max</sub>	200	kPa
Storage Temperature	T <sub>stg</sub>	-40° to +125°	°C
Operating Temperature	T <sub>A</sub>	-40° to +125°	°C

1. Exposure beyond the specified limits may cause permanent damage or degradation to the device.

Figure 1 shows a block diagram of the internal circuitry integrated on a pressure sensor chip.



**Figure 1. Fully Integrated Pressure Sensor Schematic**

## On-chip Temperature Compensation and Calibration

Figure 3 illustrates the Differential/Gauge Sensing Chip in the basic chip carrier (Case 867). A fluorosilicone gel isolates the die surface and wire bonds from the environment, while allowing the pressure signal to be transmitted to the sensor diaphragm.

The MPX5050/MPXV5050G series pressure sensor operating characteristics, and internal reliability and qualification tests are based on use of dry air as the pressure media. Media, other than dry air, may have adverse effects on sensor performance and long-term reliability. Contact the

factory for information regarding media compatibility in your application.

Figure 2 shows the sensor output signal relative to pressure input. Typical, minimum, and maximum output curves are shown for operation over a temperature range of 0° to 85°C using the decoupling circuit shown in Figure 4. The output will saturate outside of the specified pressure range.

Figure 4 shows the recommended decoupling circuit for interfacing the output of the integrated sensor to the A/D input of a microprocessor or microcontroller. Proper decoupling of the power supply is recommended.

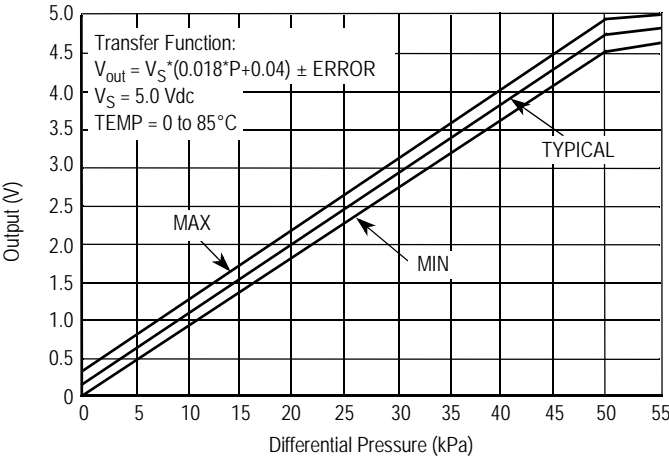


Figure 2. Output vs. Pressure Differential

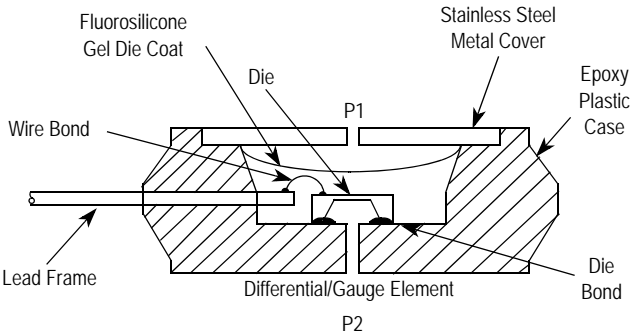


Figure 3. Cross-Sectional Diagram (not to scale)

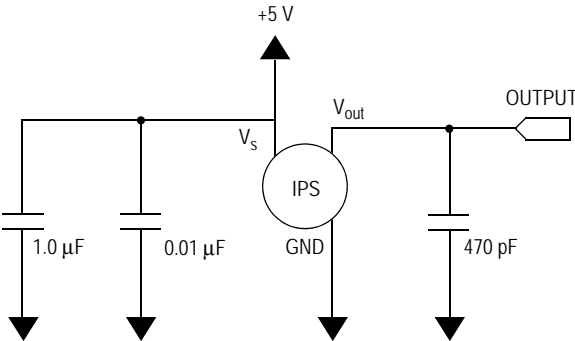
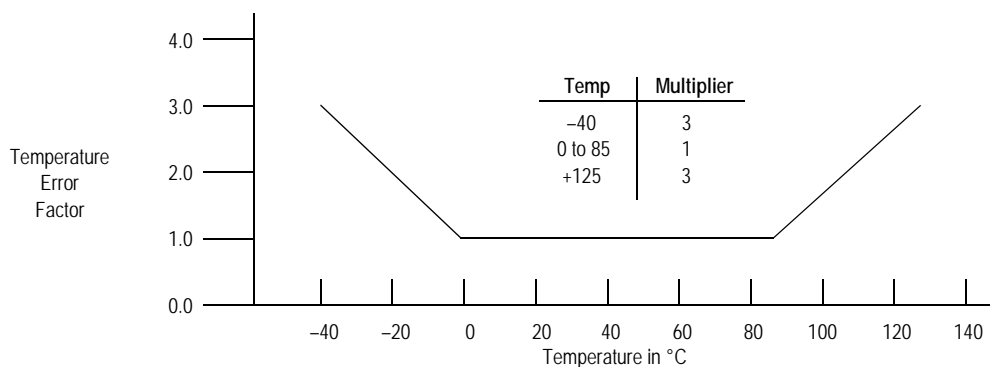


Figure 4. Recommended Power Supply Decoupling and Output Filtering  
 (For additional output filtering, please refer to Application Note AN1646)

## Transfer Function

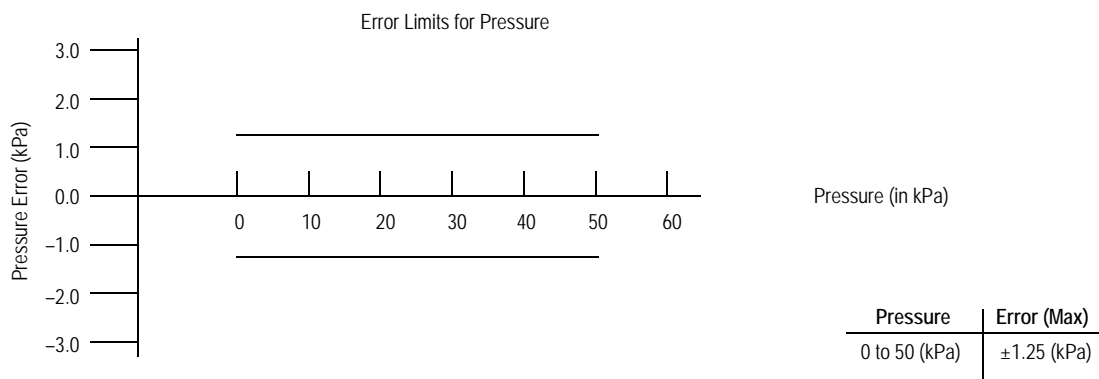
**Nominal Transfer Value:**  $V_{out} = V_S (P \times 0.018 + 0.04)$   
 $\pm (\text{Pressure Error} \times \text{Temp. Factor} \times 0.018 \times V_S)$   
 $V_S = 5.0 \text{ V} \pm 0.25 \text{ Vdc}$

## Temperature Error Band



NOTE: The Temperature Multiplier is a linear response from 0° to -40°C and from 85° to 125°C.

## Pressure Error Band



## PRESSURE (P1)/VACUUM (P2) SIDE IDENTIFICATION TABLE

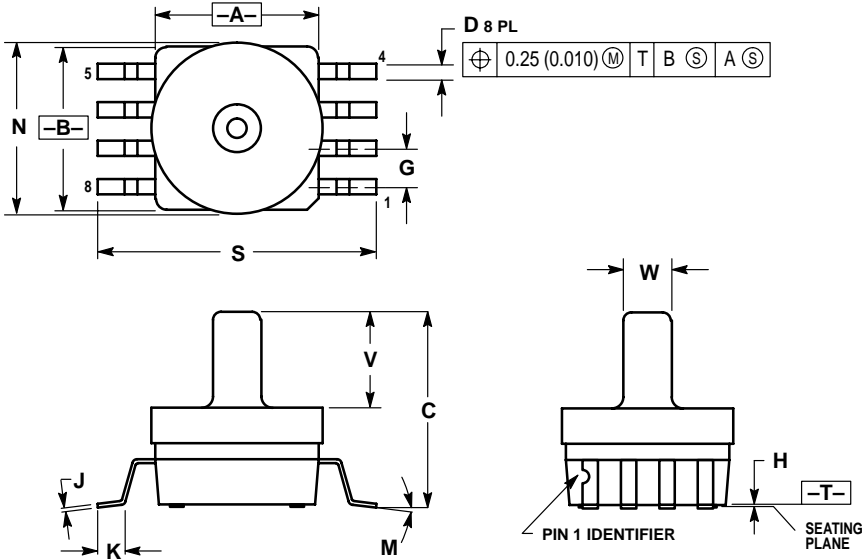
Freescale designates the two sides of the pressure sensor as the Pressure (P1) side and the Vacuum (P2) side. The Pressure (P1) side is the side containing fluorosilicone gel which protects the die from harsh media. The MPX pressure

sensor is designed to operate with positive differential pressure applied,  $P1 > P2$ .

The Pressure (P1) side may be identified by using the table below:

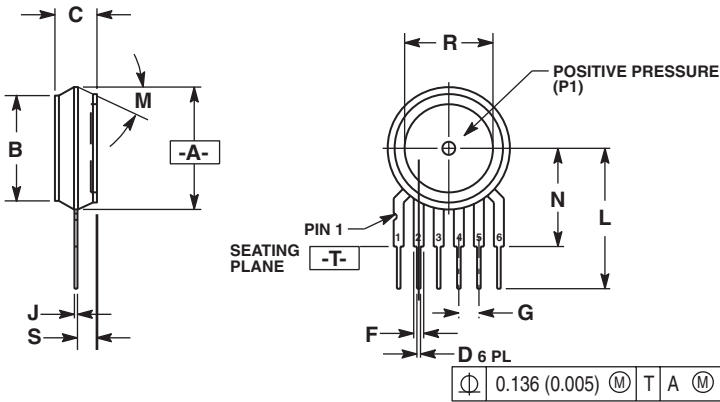
Part Number	Case Type	Pressure (P1) Side Identifier
MPX5050D	867	Stainless Steel Cap
MPX5050DP	867C	Side with Part Marking
MPX5050GP	867B	Side with Port Attached
MPXV5050GP	1369	Side with Port Attached
MPXV5050DP	1351	Side with Part Marking
MPXV5050GC6U/T1	482A	Vertical Port Attached

# PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006).
  5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.

**CASE 482A-01  
ISSUE A  
UNIBODY PACKAGE**



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION -A- IS INCLUSIVE OF THE MOLD STOP RING. MOLD STOP RING NOT TO EXCEED 16.00 (0.630).

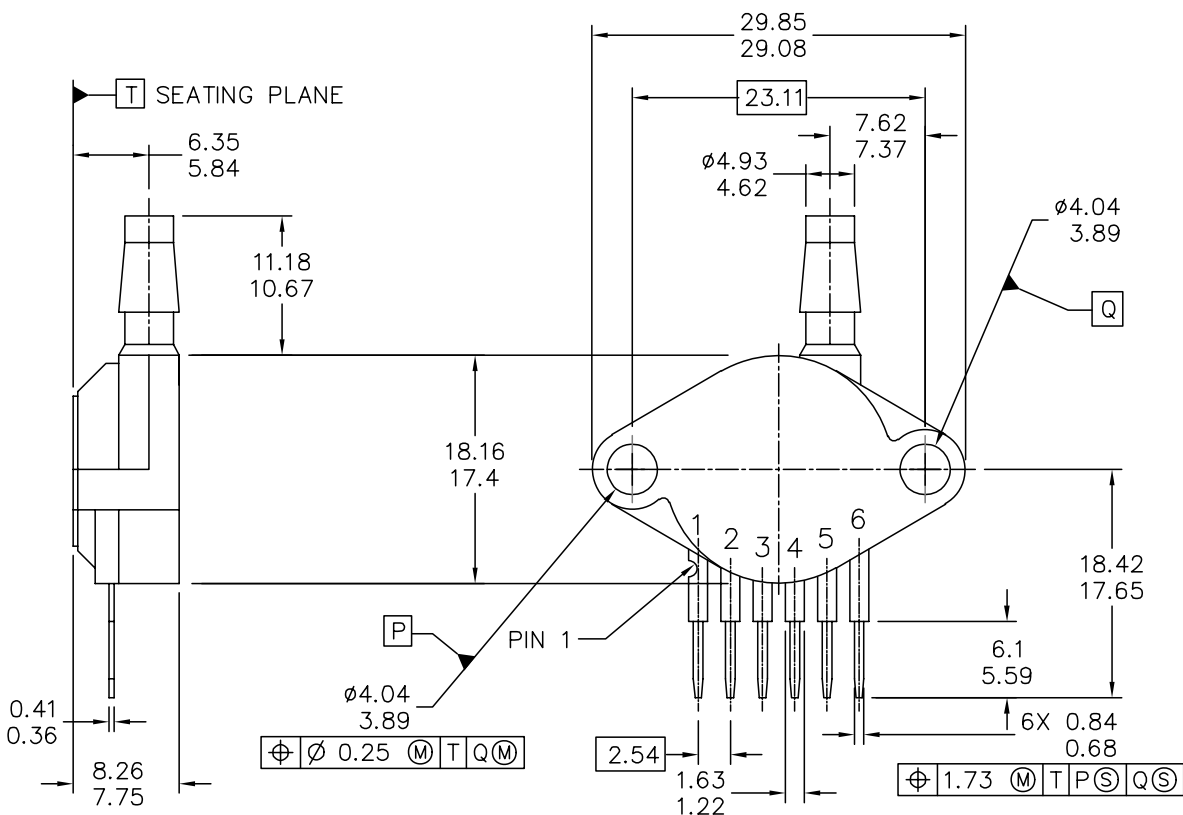
STYLE 1:  
PIN 1: VOUT  
2. GROUND  
3. VCC  
4. V1  
5. V2  
6. VEX

STYLE 2:  
PIN 1: OPEN  
2. GROUND  
3. -VOUT  
4. VSUPPLY  
5. +VOUT  
6. OPEN

STYLE 3:  
PIN 1: OPEN  
2. GROUND  
3. +VOUT  
4. +VSUPPLY  
5. -VOUT  
6. OPEN

**CASE 867-08  
ISSUE N  
UNIBODY PACKAGE**

# PACKAGE DIMENSIONS



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TITLE: SENSOR, 6 LEAD UNIBODY CELL, AP & GP 01ASB09087B		DOCUMENT NO: 98ASB42796B	REV: G
		CASE NUMBER: 867B-04	28 JUL 2005
		STANDARD: NON-JEDEC	

**CASE 867B-04  
ISSUE G  
UNIBODY PACKAGE**

# PACKAGE DIMENSIONS

## NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. 867B-01 THRU -3 OBSOLETE, NEW STANDARD 867B-04.

## STYLE 1:

- PIN 1: V OUT  
2: GROUND  
3: VCC  
4: V1  
5: V2  
6: V EX

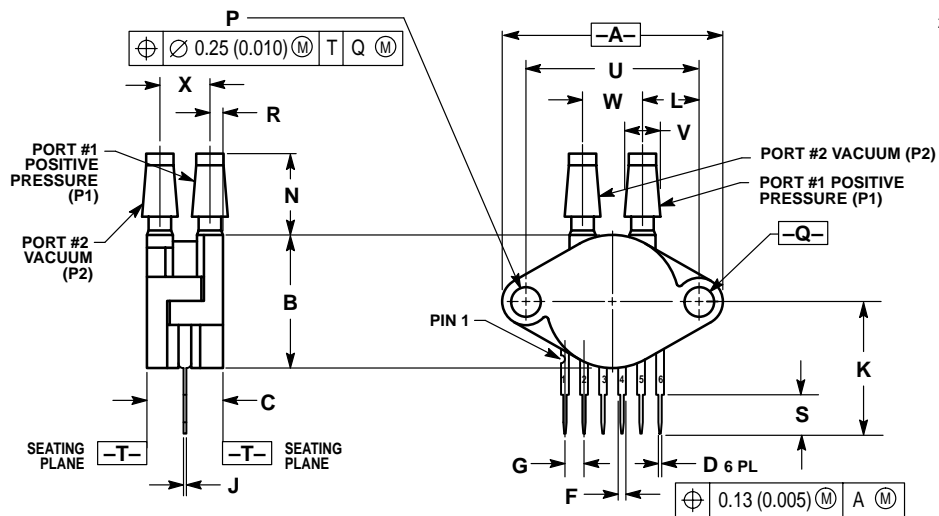
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TITLE: SENSOR, 6 LEAD UNIBODY CELL, AP & GP 01ASB09087B	DOCUMENT NO: 98ASB42796B		REV: G
	CASE NUMBER: 867B-04		28 JUL 2005
	STANDARD: NON-JEDEC		

PAGE 2 OF 2

**CASE 867B-04  
ISSUE G  
UNIBODY PACKAGE**



# PACKAGE DIMENSIONS



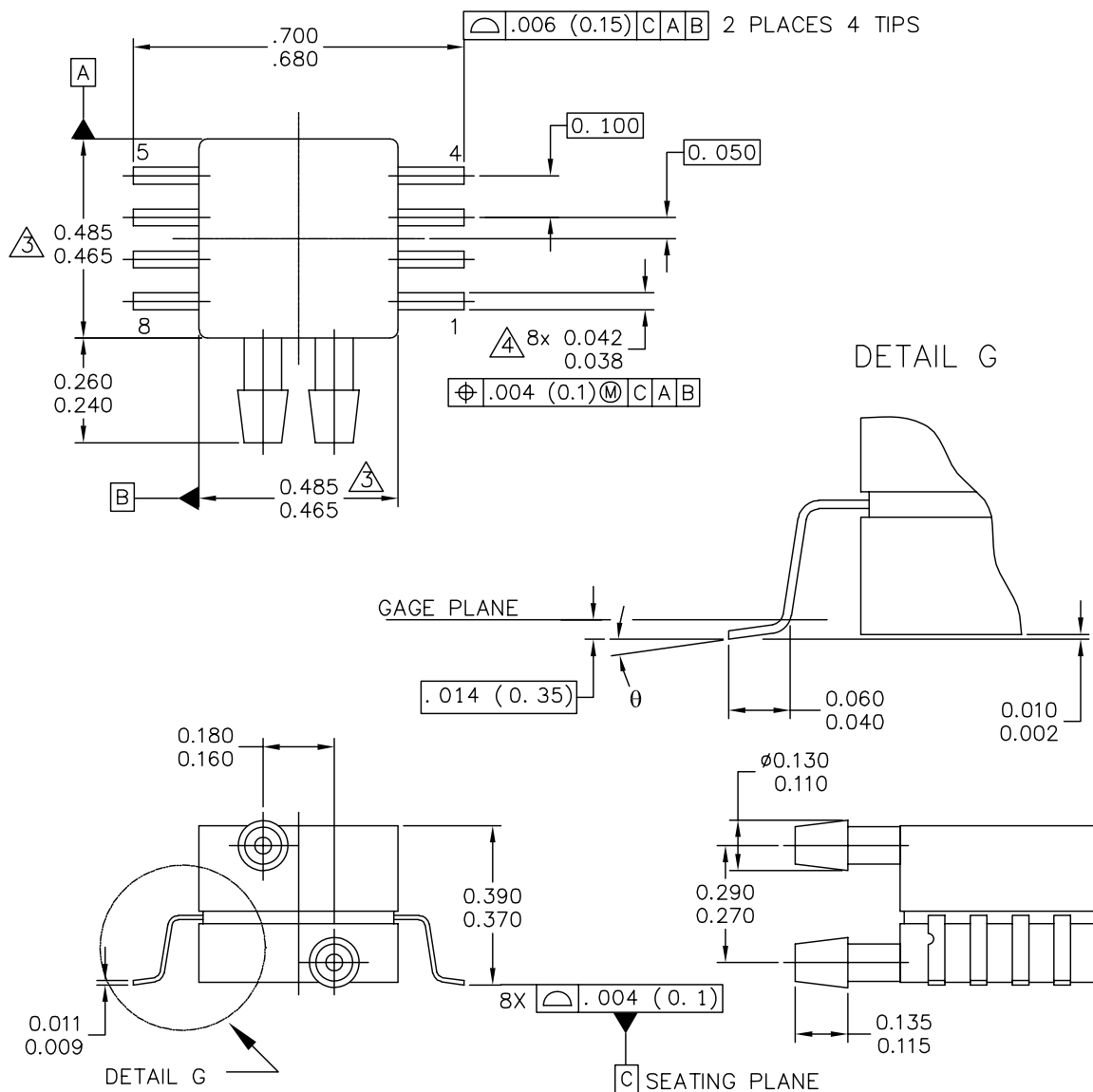
- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.145	1.175	29.08	29.85
B	0.685	0.715	17.40	18.16
C	0.405	0.435	10.29	11.05
D	0.027	0.033	0.68	0.84
F	0.048	0.064	1.22	1.63
G	0.100 BSC		2.54 BSC	
J	0.014	0.016	0.36	0.41
K	0.695	0.725	17.65	18.42
L	0.290	0.300	7.37	7.62
N	0.420	0.440	10.67	11.18
P	0.153	0.159	3.89	4.04
Q	0.153	0.159	3.89	4.04
R	0.063	0.083	1.60	2.11
S	0.220	0.240	5.59	6.10
U	0.910 BSC		23.11 BSC	
V	0.182	0.194	4.62	4.93
W	0.310	0.330	7.87	8.38
X	0.248	0.278	6.30	7.06

- STYLE 1:
1. V<sub>OUT</sub>
  2. GROUND
  3. V<sub>CC</sub>
  4. V<sub>I</sub>
  5. V<sub>2</sub>
  6. V<sub>EX</sub>

**CASE 867C-05**  
**ISSUE F**  
**UNIBODY PACKAGE**

# PACKAGE DIMENSIONS



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TITLE:  8 LD SNSR, DUAL PORT			DOCUMENT NO: 98ASA99255D		REV: A
			CASE NUMBER: 1351-01		27 JUL 2005
			STANDARD: NON-JEDEC		

PAGE 1 OF 2

**CASE 1351-01  
ISSUE A  
SMALL OUTLINE PACKAGE**

MPX5050

## PACKAGE DIMENSIONS

### NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 PER SIDE.
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 MAXIMUM.

#### STYLE 1:

PIN 1: GND  
PIN 2: +Vout  
PIN 3: Vs  
PIN 4: -Vout  
PIN 5: N/C  
PIN 6: N/C  
PIN 7: N/C  
PIN 8: N/C

#### STYLE 2:

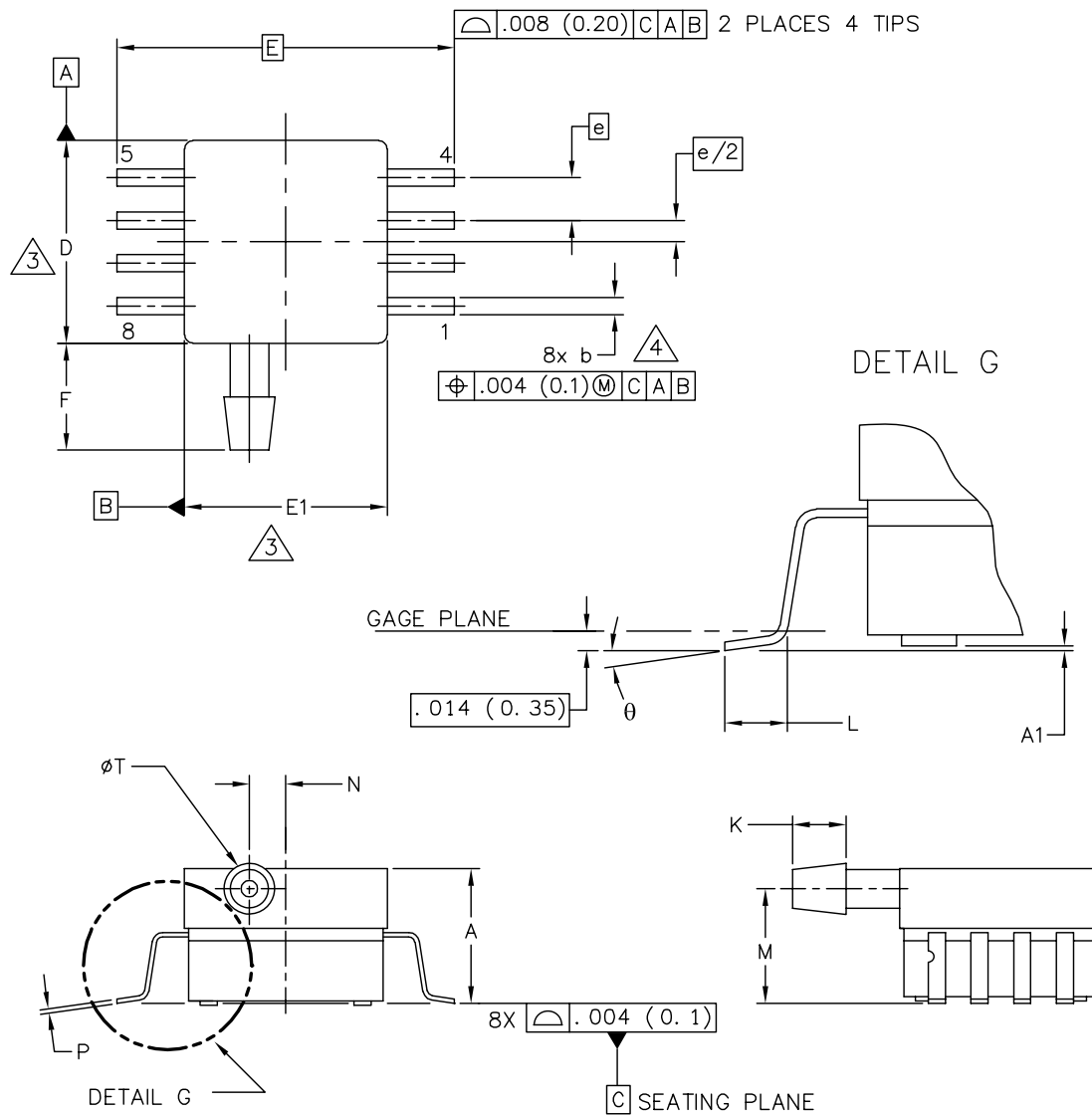
PIN 1: N/C  
PIN 2: Vs  
PIN 3: GND  
PIN 4: Vout  
PIN 5: N/C  
PIN 6: N/C  
PIN 7: N/C  
PIN 8: N/C

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TITLE:  8 LD SNSR, DUAL PORT		DOCUMENT NO: 98ASA99255D		REV: A
		CASE NUMBER: 1351-01		27 JUL 2005
		STANDARD: NON-JEDEC		

PAGE 2 OF 2

**CASE 1351-01  
ISSUE A  
SMALL OUTLINE PACKAGE**

# PACKAGE DIMENSIONS



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TITLE:  8 LD SOP, SIDE PORT		DOCUMENT NO: 98ASA99303D	REV: B
		CASE NUMBER: 1369-01	24 MAY 2005
		STANDARD: NON-JEDEC	

PAGE 1 OF 2

**CASE 1369-01  
ISSUE B  
SMALL OUTLINE PACKAGE**

MPX5050

# PACKAGE DIMENSIONS

## NOTES:

1. CONTROLLING DIMENSION: INCH

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.  
MOLD FLASH AND PROTRUSIONS SHALL NOT EXCEED .006 (0.152) PER SIDE.

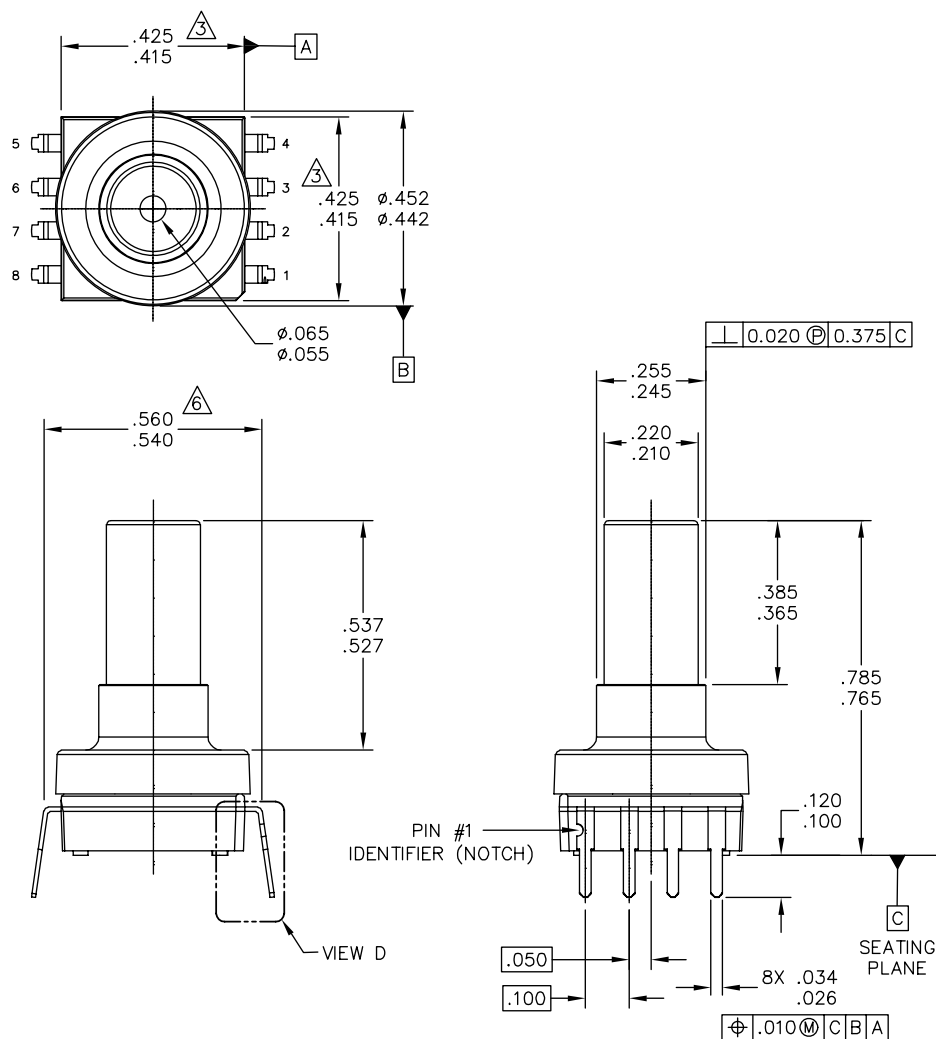
4. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE .008 (0.203) MAXIMUM.

DIM	INCHES		MILLIMETERS		DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.300	.330	7.11	7.62	θ	0°	7°	0°	7°
A1	.002	.010	0.05	0.25	—	---	---	---	---
b	.038	.042	0.96	1.07	—	---	---	---	---
D	.465	.485	11.81	12.32	—	---	---	---	---
E	.717 BSC		18.21 BSC		—	---	---	---	---
E1	.465	.485	11.81	12.32	—	---	---	---	---
e	.100 BSC		2.54 BSC		—	---	---	---	---
F	.245	.255	6.22	6.47	—	---	---	---	---
K	.120	.130	3.05	3.30	—	---	---	---	---
L	.061	.071	1.55	1.80	—	---	---	---	---
M	.270	.290	6.86	7.36	—	---	---	---	---
N	.080	.090	2.03	2.28	—	---	---	---	---
P	.009	.011	0.23	0.28	—	---	---	---	---
T	.115	.125	2.92	3.17	—	---	---	---	---
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TITLE:  8 LD SOP, SIDE PORT					DOCUMENT NO: 98ASA99303D				REV: B
					CASE NUMBER: 1369-01				24 MAY 2005
					STANDARD: NON-JEDEC				

PAGE 2 OF 2

**CASE 1369-01  
ISSUE B  
SMALL OUTLINE PACKAGE**

## PACKAGE DIMENSIONS



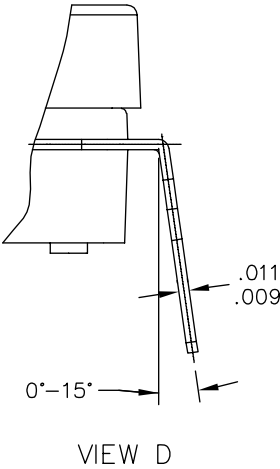
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TITLE:  SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D		REV: D	
	CASE NUMBER: 1560-03		25 FEB 2009	
	STANDARD: NON-JEDEC			

PAGE 1 OF 3

**CASE 1560-03  
ISSUE D  
SMALL OUTLINE PACKAGE**

**MPX5050**

PACKAGE DIMENSIONS



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TITLE:  SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH		DOCUMENT NO: 98ASA10611D		REV: D	
		CASE NUMBER: 1560-03		25 FEB 2009	
		STANDARD: NON-JEDEC			

CASE 1560-03  
ISSUE D  
SMALL OUTLINE PACKAGE

# PACKAGE DIMENSIONS

## NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M – 1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION IS .006.
5. ALL VERTICAL SURFACES 5° TYPICAL DRAFT.
6. DIMENSION TO CENTER OF LEAD WHEN FORMED PARALLEL.

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TITLE: SO, 8 I/O, .420 X .420 PKG, .100 IN PITCH	DOCUMENT NO: 98ASA10611D		REV: D
	CASE NUMBER: 1560-03		25 FEB 2009
	STANDARD: NON-JEDEC		

PAGE 3 OF 3

**CASE 1560-03  
ISSUE D  
SMALL OUTLINE PACKAGE**

**MPX5050**



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